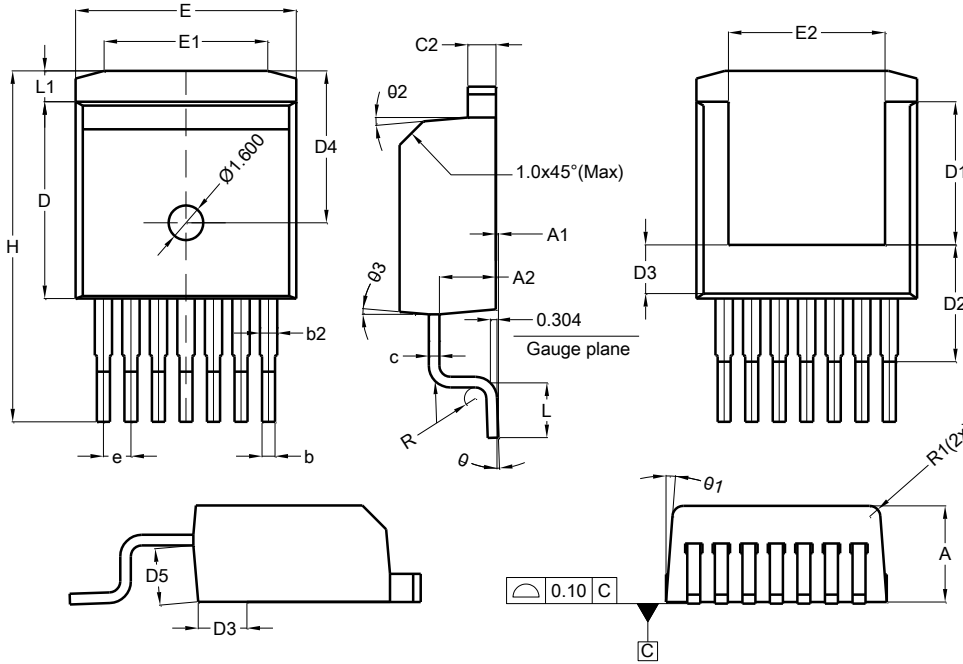


## Package Outline Dimensions

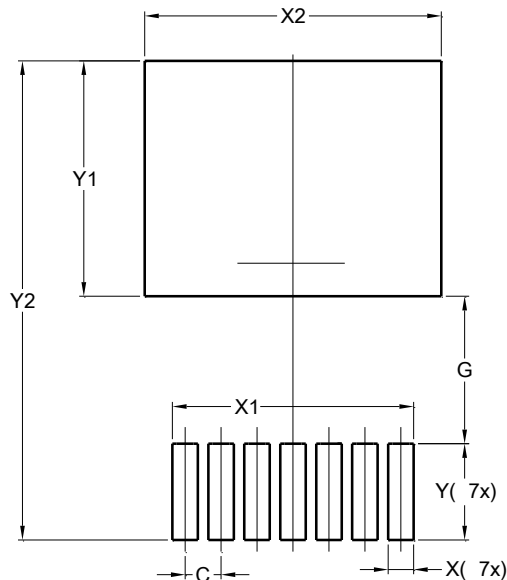
TO263-7 (Type B)



TO263-7 (Type B)			
Dim	Min	Max	Typ
A	4.30	4.57	4.435
A1	0.00	0.25	0.125
A2	2.595 REF		
b	0.50	0.70	0.60
b2	0.600	1.000	0.800
c	0.33	0.65	0.490
c2	1.17	1.40	1.285
D	9.025	9.125	9.075
D1	6.50	6.70	6.60
D2	5.39 REF		
D3	2.148 MIN		
D4	7.00 REF		
D5	2.555	--	2.605
e	1.27 TYP		
E	10.13	10.23	10.18
E1	6.50	8.60	7.55
E2	6.778	7.665	7.223
H	15.043	17.313	16.178
L	2.324	2.700	2.512
L1	0.968	1.868	1.418
R	0.506 REF		
R1	0.500 REF		
$\theta$	0°	8°	4°
$\theta_1$	4.5°	5.5°	5°
$\theta_2$	4°	6°	5°
$\theta_3$	4°	6°	5°
All Dimensions in mm			

## Suggested Pad Layout

TO263-7 (Type B)



Dimensions	Value (in mm)
C	1.270
G	5.210
X	0.900
X1	8.520
X2	10.480
Y	3.400
Y1	8.318
Y2	16.928

### ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.